

RELIABILITY MONITOR REPORT
FOR

TSOC Package

Dallas Semiconductor

4401 South Beltwood Parkway
Dallas, TX 75244-3292

This Report was prepared by
Dallas Semiconductor Reliability Engineering

Summary:

The data in the tables that follow was generated as the result of an on-going Package Reliability Monitor. The assemblies covered by this package monitor are:

ASSY SITE	PINS	PACKAGE		
Hana	6	TSOC	Hana	6 TSOC (Pb-Free)
OSEP	6	TSOC	OSEP	6 TSOC (Pb-Free)

Note: Due to the nature of the construction on this assembly, there is no operating life data collected.

The reliability data follows. At the start of this data is a description of the assembly vehicle used to generate this reliability data. The next section is the detailed reliability data for each stress. The reliability data section includes the latest data available. This report covers data between 4/1/2006 and 3/31/2007.

Assembly Information:

Package Type: TSOC 150x1.25
 Flammability: UL 94-V0
 Moisture Sensitivity (JEDEC J-STD20A) Level 1
 Date Code Range: 0603 to 0603

PRECONDITIONING LEVEL 1

DESCRIPTION	DATE CODE	TEST VEHICLE	CONDITION	READPOINT	QUANTITY	FAILS	FA NO
ULTRASOUND	0603	DS2502	J-STD-020		4	0	
STORAGE LIFE	0603	DS2502	125C	24	HRS	151	
MOISTURE SOAK			85 C/85% R.H.	168	HRS	151	
CONVECTION REFLOW			235C +/-0C	3	PASS	151	0
PRECONDITION U/S	0603	DS2502	J-STD-020		4	0	
Total:						0	

TEMPERATURE CYCLE

DESCRIPTION	DATE CODE	TEST VEHICLE	CONDITION	READPOINT	QUANTITY	FAILS	FA NO
TEMP CYCLE	0603	DS2502	-55C TO 125C	1000	CYS	74	0
Total:						0	

UNBIASED MOISTURE RESISTANCE

DESCRIPTION	DATE CODE	TEST VEHICLE	CONDITION	READPOINT	QUANTITY	FAILS	FA NO
AUTOCLAVE	0603	DS2502	121C, 2 ATM STEAM, UNBIASED	96	HRS	73	0
Total:						0	